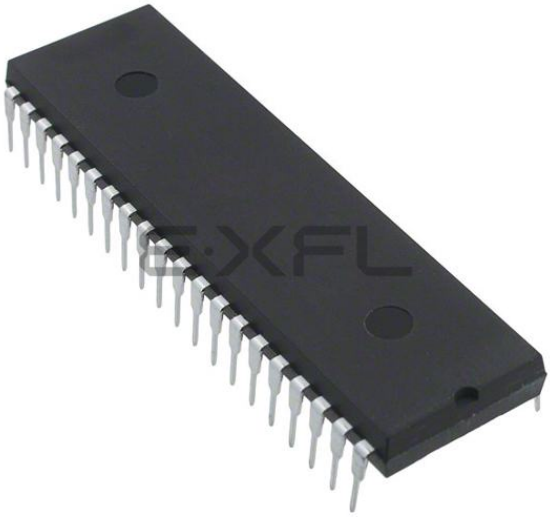

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PSMC, PWM, WDT
Number of I/O	35
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 5.5V
Data Converters	A/D 14x12b; D/A 1x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	40-DIP (0.600", 15.24mm)
Supplier Device Package	40-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f1784-i-p

3.0 MEMORY ORGANIZATION

These devices contain the following types of memory:

- Program Memory
  - Configuration Words
  - Device ID
  - User ID
  - Flash Program Memory
- Data Memory
  - Core Registers
  - Special Function Registers
  - General Purpose RAM
  - Common RAM
- Data EEPROM memory(1)

Note 1: The Data EEPROM Memory and the method to access Flash memory through the EECON registers is described in **Section 12.0 "Data EEPROM and Flash Program Memory Control"**.

The following features are associated with access and control of program memory and data memory:

- PCL and PCLATH
- Stack
- Indirect Addressing

3.1 Program Memory Organization

The enhanced mid-range core has a 15-bit program counter capable of addressing a 32K x 14 program memory space. Table 3-1 shows the memory sizes implemented for the PIC16(L)F1784/6/7 family. Accessing a location above these boundaries will cause a wrap-around within the implemented memory space. The Reset vector is at 0000h and the interrupt vector is at 0004h (see Figures 3-1 and 3-2).

TABLE 3-1: DEVICE SIZES AND ADDRESSES

Device	Program Memory Space (Words)	Last Program Memory Address
PIC16(L)F1784	4,096	0FFFh
PIC16(L)F1786/7	8,192	1FFFh

TABLE 3-6: PIC16(L)F1784 MEMORY MAP (BANKS 8-31)

BANK 8		BANK 9		BANK 10		BANK 11		BANK 12		BANK 13		BANK 14		BANK 15	
400h	Core Registers (Table 3-2)	480h	Core Registers (Table 3-2)	500h	Core Registers (Table 3-2)	580h	Core Registers (Table 3-2)	600h	Core Registers (Table 3-2)	680h	Core Registers (Table 3-2)	700h	Core Registers (Table 3-2)	780h	Core Registers (Table 3-2)
40Bh		48Bh		50Bh		58Bh		60Bh		68Bh		70Bh		78Bh	
40Ch	Unimplemented Read as '0'	48Ch	Unimplemented Read as '0'	50Ch	Unimplemented Read as '0'	58Ch	Unimplemented Read as '0'	60Ch	Unimplemented Read as '0'	68Ch	Unimplemented Read as '0'	70Ch	Unimplemented Read as '0'	78Ch	Unimplemented Read as '0'
				510h											
				511h	OPA1CON										
				512h	—										
				513h	OPA2CON										
				514h	Unimplemented Read as '0'										
				519h											
				51Ah	CLKRCON										
				51Bh	Unimplemented Read as '0'										
46Fh		4EFh		56Fh		5EFh		66Fh		6EFh		76Fh		7EFh	
470h	Common RAM (Accesses 70h – 7Fh)	4F0h	Common RAM (Accesses 70h – 7Fh)	570h	Common RAM (Accesses 70h – 7Fh)	5F0h	Common RAM (Accesses 70h – 7Fh)	670h	Common RAM (Accesses 70h – 7Fh)	6F0h	Common RAM (Accesses 70h – 7Fh)	770h	Common RAM (Accesses 70h – 7Fh)	7F0h	Common RAM (Accesses 70h – 7Fh)
47Fh		4FFh		57Fh		5FFh		67Fh		6FFh		77Fh		7FFh	

BANK 16		BANK 17		BANK 18		BANK 19		BANK 20		BANK 21		BANK 22		BANK 23	
800h	Core Registers (Table 3-2)	880h	Core Registers (Table 3-2)	900h	Core Registers (Table 3-2)	980h	Core Registers (Table 3-2)	A00h	Core Registers (Table 3-2)	A80h	Core Registers (Table 3-2)	B00h	Core Registers (Table 3-2)	B80h	Core Registers (Table 3-2)
80Bh		88Bh		90Bh		98Bh		A0Bh		A8Bh		B0Bh		B8Bh	
80Ch	See Table 3-10	88Ch	Unimplemented Read as '0'	90Ch	Unimplemented Read as '0'	98Ch	Unimplemented Read as '0'	A0Ch	Unimplemented Read as '0'	A8Ch	Unimplemented Read as '0'	B0Ch	Unimplemented Read as '0'	B8Ch	Unimplemented Read as '0'
86Fh		8EFh		96Fh		9EFh		A6Fh		AEFh		B6Fh		BEFh	
870h	Common RAM (Accesses 70h – 7Fh)	8F0h	Common RAM (Accesses 70h – 7Fh)	970h	Common RAM (Accesses 70h – 7Fh)	9F0h	Common RAM (Accesses 70h – 7Fh)	A70h	Common RAM (Accesses 70h – 7Fh)	AF0h	Common RAM (Accesses 70h – 7Fh)	B70h	Common RAM (Accesses 70h – 7Fh)	BF0h	Common RAM (Accesses 70h – 7Fh)
87Fh		8FFh		97Fh		9FFh		A7Fh		AFFh		B7Fh		BFFh	

BANK 24		BANK 25		BANK 26		BANK 27		BANK 28		BANK 29		BANK 30		BANK 31	
C00h	Core Registers (Table 3-2)	C80h	Core Registers (Table 3-2)	D00h	Core Registers (Table 3-2)	D80h	Core Registers (Table 3-2)	E00h	Core Registers (Table 3-2)	E80h	Core Registers (Table 3-2)	F00h	Core Registers (Table 3-2)	F80h	Core Registers (Table 3-2)
C0Bh		C8Bh		D0Bh		D8Bh		E0Bh		E8Bh		F0Bh		F8Bh	
C0Ch	Unimplemented Read as '0'	C8Ch	Unimplemented Read as '0'	D0Ch	Unimplemented Read as '0'	D8Ch	Unimplemented Read as '0'	E0Ch	Unimplemented Read as '0'	E8Ch	Unimplemented Read as '0'	F0Ch	Unimplemented Read as '0'	F8Ch	See Table 3-9
C6Fh		CEFh		D6Fh		DEFh		E6Fh		EEFh		F6Fh		FEFh	
C70h	Common RAM (Accesses 70h – 7Fh)	CF0h	Common RAM (Accesses 70h – 7Fh)	D70h	Common RAM (Accesses 70h – 7Fh)	DF0h	Common RAM (Accesses 70h – 7Fh)	E70h	Common RAM (Accesses 70h – 7Fh)	EF0h	Common RAM (Accesses 70h – 7Fh)	F70h	Common RAM (Accesses 70h – 7Fh)	FF0h	Common RAM (Accesses 70h – 7Fh)
C7Fh		CFFh		D7Fh		DFFh		E7Fh		EFFh		F7Fh		FFFh	

Legend: = Unimplemented data memory locations, read as '0'

TABLE 3-12: SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
Bank 16 (Continued)											
831h	PSMC2CON	PSMC2EN	PSMC2LD	PSMC2DBFE	PSMC2DBRE	P2MODE<3:0>				0000 0000	0000 0000
832h	PSMC2MDL	P2MDLEN	P2MDLPOL	P2MDLBIT	—	P2MSRC<3:0>				000- 0000	000- 0000
833h	PSMC2SYNC	P2POFST	P2PRPOL	P2DCPOL	—	—	—	P2SYNC<1:0>		000- --00	000- --00
834h	PSMC2CLK	—	—	P2CPRE<1:0>		—	—	P2CSRC<1:0>		--00 --00	--00 --00
835h	PSMC2OEN	—	—	—	—	—	—	P2OEB	P2OEA	---- --00	---- --00
836h	PSMC2POL	—	P2INPOL	—	—	—	—	P2POLB	P2POLA	-0-- --00	-0-- --00
837h	PSMC2BLNK	—	—	P2FEBM<1:0>		—	—	P2REBM<1:0>		--00 --00	--00 --00
838h	PSMC2REBS	P2REBIN	—	—	P2REBSC4	P2REBSC3	P2REBSC2	P2REBSC1	—	0--0 000-	0--0 000-
839h	PSMC2FEBS	P2FEBIN	—	—	P2FEBSC4	P2FEBSC3	P2FEBSC2	P2FEBSC1	—	0--0 000-	0--0 000-
83Ah	PSMC2PHS	P2PHSIN	—	—	P2PHSC4	P2PHSC3	P2PHSC2	P2PHSC1	P2PHST	0--0 0000	0--0 0000
83Bh	PSMC2DCS	P2DCSIN	—	—	P2DCSC4	P2DCSC3	P2DCSC2	P2DCSC1	P2DCST	0--0 0000	0--0 0000
83Ch	PSMC2PRS	P2PRSIN	—	—	P2PRSC4	P2PRSC3	P2PRSC2	P2PRSC1	P2PRST	0--0 0000	0--0 0000
83Dh	PSMC2ASDC	P2ASE	P2ASDEN	P2ARSEN	—	—	—	—	P2ASDOV	000- ---0	000- ---0
83Eh	PSMC2ASDL	—	—	P2ASDLF	P2ASDLE	P2ASDLD	P2ASDLC	P2ASDLB	P2ASDLA	--00 0000	--00 0000
83Fh	PSMC2ASDS	P2ASDSIN	—	—	P2ASDSC4	P2ASDSC3	P2ASDSC2	P2ASDSC1	—	0--0 000-	0--0 000-
840h	PSMC2INT	P2TOVIE	P2TPHIE	P2TDCIE	P2TPRIE	P2TOVIF	P2TPHIF	P2TDCIF	P2TPRIF	0000 0000	0000 0000
841h	PSMC2PHL	Phase Low Count								0000 0000	0000 0000
842h	PSMC2PHH	Phase High Count								0000 0000	0000 0000
843h	PSMC2DCL	Duty Cycle Low Count								0000 0000	0000 0000
844h	PSMC2DCH	Duty Cycle High Count								0000 0000	0000 0000
845h	PSMC2PRL	Period Low Count								0000 0000	0000 0000
846h	PSMC2PRH	Period High Count								0000 0000	0000 0000
847h	PSMC2TMRL	Time base Low Counter								0000 0001	0000 0001
848h	PSMC2TMRH	Time base High Counter								0000 0000	0000 0000
849h	PSMC2DBR	rising Edge Dead-band Counter								0000 0000	0000 0000
84Ah	PSMC2DBF	Falling Edge Dead-band Counter								0000 0000	0000 0000
84Bh	PSMC2BLKR	rising Edge Blanking Counter								0000 0000	0000 0000
84Ch	PSMC2BLKF	Falling Edge Blanking Counter								0000 0000	0000 0000
84Dh	PSMC2FFA	—	—	—	—	Fractional Frequency Adjust Register				---- 0000	---- 0000
84Eh	PSMC2STR0	—	—	—	—	—	—	P2STRB	P2STRA	---- --01	---- --01
84Fh	PSMC2STR1	P2SYNC	—	—	—	—	—	P2LSMEN	P2HSMEN	0--- --00	0--- --00
850h	—	Unimplemented								—	—

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, read as '0', r = reserved. Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from any bank.
2: Unimplemented, read as '1'.
3: PIC16(L)F1784/7 only.
4: PIC16F1784/6/7 only.

TABLE 3-12: SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
Bank 31											
F8Ch to FE3h	—	Unimplemented								—	—
FE4h	STATUS_ SHAD	—	—	—	—	—	Z	DC	C	---- -xxx	---- -uuu
FE5h	WREG_SHAD	Working Register Shadow								xxxx xxxx	uuuu uuuu
FE6h	BSR_SHAD	—	—	—	Bank Select Register Shadow					---x xxxx	---u uuuu
FE7h	PCLATH_ SHAD	—	Program Counter Latch High Register Shadow							-xxx xxxx	uuuu uuuu
FE8h	FSR0L_SHAD	Indirect Data Memory Address 0 Low Pointer Shadow								xxxx xxxx	uuuu uuuu
FE9h	FSR0H_ SHAD	Indirect Data Memory Address 0 High Pointer Shadow								xxxx xxxx	uuuu uuuu
FEAh	FSR1L_SHAD	Indirect Data Memory Address 1 Low Pointer Shadow								xxxx xxxx	uuuu uuuu
FEBh	FSR1H_ SHAD	Indirect Data Memory Address 1 High Pointer Shadow								xxxx xxxx	uuuu uuuu
FECh	—	Unimplemented								—	—
FEDh	STKPTR	—	—	—	Current Stack Pointer					---1 1111	---1 1111
FEEh	TOSL	Top of Stack Low byte								xxxx xxxx	uuuu uuuu
FEFh	TOSH	—	Top of Stack High byte							-xxx xxxx	-uuu uuuu

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, read as '0', r = reserved. Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from any bank.

2: Unimplemented, read as '1'.

3: PIC16(L)F1784/7 only.

4: PIC16F1784/6/7 only.

4.0 DEVICE CONFIGURATION

Device configuration consists of Configuration Words, Code Protection and Device ID.

4.1 Configuration Words

There are several Configuration Word bits that allow different oscillator and memory protection options. These are implemented as Configuration Word 1 at 8007h and Configuration Word 2 at 8008h.

Note:	The $\overline{\text{DEBUG}}$ bit in Configuration Words is managed automatically by device development tools including debuggers and programmers. For normal device operation, this bit should be maintained as a '1'.

13.6 Register Definitions: PORTB

REGISTER 13-11: PORTB: PORTB REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **RB<7:0>**: PORTB General Purpose I/O Pin bits(1)
1 = Port pin is ≥ VIH
0 = Port pin is ≤ VIL

Note 1: Writes to PORTB are actually written to corresponding LATB register. Reads from PORTB register is return of actual I/O pin values.

REGISTER 13-12: TRISB: PORTB TRI-STATE REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **TRISB<7:0>:** PORTB Tri-State Control bits
1 = PORTB pin configured as an input (tri-stated)
0 = PORTB pin configured as an output

REGISTER 13-13: LATB: PORTB DATA LATCH REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
LATB7	LATB6	LATB5	LATB4	LATB3	LATB2	LATB1	LATB0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **LATB<7:0>**: PORTB Output Latch Value bits(1)

Note 1: Writes to PORTB are actually written to corresponding LATB register. Reads from PORTB register is return of actual I/O pin values.

REGISTER 13-14: ANSELB: PORTB ANALOG SELECT REGISTER

U-0	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
—	ANSB6	ANSB5	ANSB4	ANSB3	ANSB2	ANSB1	ANSB0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **Unimplemented:** Read as '0'

bit 6-0 **ANSB<6:0>**: Analog Select between Analog or Digital Function on pins RB<6:0>, respectively
0 = Digital I/O. Pin is assigned to port or digital special function.
1 = Analog input. Pin is assigned as analog input(1). Digital input buffer disabled.

Note 1: When setting a pin to an analog input, the corresponding TRIS bit must be set to Input mode in order to allow external control of the voltage on the pin.

REGISTER 13-15: WPUB: WEAK PULL-UP PORTB REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
WPUB7	WPUB6	WPUB5	WPUB4	WPUB3	WPUB2	WPUB1	WPUB0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **WPUB<7:0>**: Weak Pull-up Register bits
1 = Pull-up enabled
0 = Pull-up disabled

Note 1: Global $\overline{\text{WPUEN}}$ bit of the OPTION_REG register must be cleared for individual pull-ups to be enabled.
2: The weak pull-up device is automatically disabled if the pin is in configured as an output.

REGISTER 24-22: PSMCxDCL: PSMC DUTY CYCLE COUNT LOW BYTE REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
PSMCxDCL<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **PSMCxDCL<7:0>:** 16-bit Duty Cycle Count Least Significant bits
= PSMCxDC<7:0>

REGISTER 24-23: PSMCxDCH: PSMC DUTY CYCLE COUNT HIGH REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
PSMCxDCH<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **PSMCxDCH<7:0>:** 16-bit Duty Cycle Count Most Significant bits
= PSMCxDC<15:8>

26.2.3 SPI MASTER MODE

The master can initiate the data transfer at any time because it controls the SCK line. The master determines when the slave (Processor 2, Figure 26-5) is to broadcast data by the software protocol.

In Master mode, the data is transmitted/received as soon as the SSPBUF register is written to. If the SPI is only going to receive, the SDO output could be disabled (programmed as an input). The SSPSR register will continue to shift in the signal present on the SDI pin at the programmed clock rate. As each byte is received, it will be loaded into the SSPBUF register as if a normal received byte (interrupts and Status bits appropriately set).

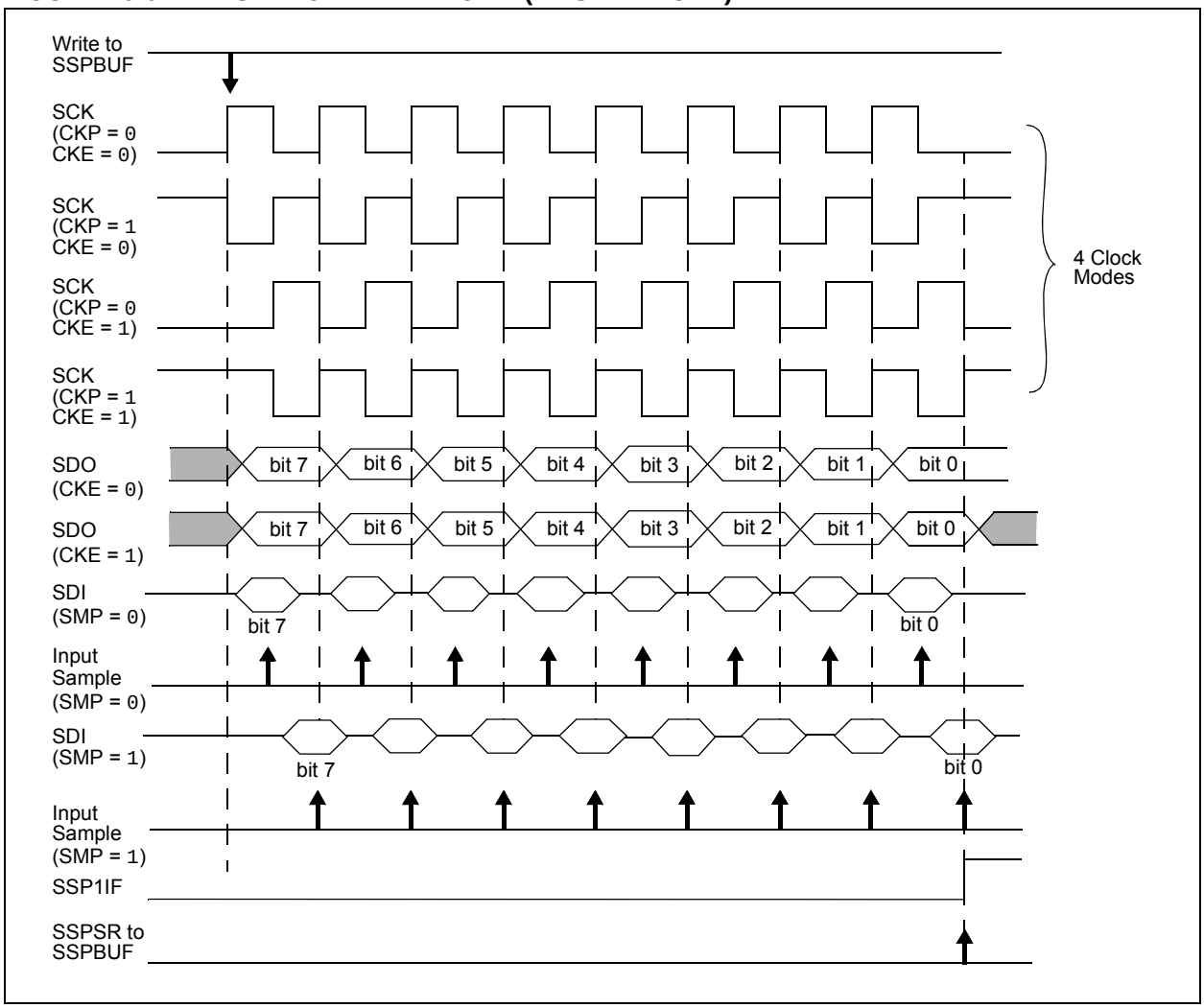
The clock polarity is selected by appropriately programming the CKP bit of the SSPCON1 register and the CKE bit of the SSPSTAT register. This then, would give waveforms for SPI communication as shown in Figure 26-6, Figure 26-8 and Figure 26-9, where the MSB is transmitted first. In Master mode, the SPI clock rate (bit rate) is user programmable to be one of the following:

- FOSC/4 (or TCY)
- FOSC/16 (or 4 * TCY)
- FOSC/64 (or 16 * TCY)
- Timer2 output/2
- Fosc/(4 * (SSPADD + 1))

Figure 26-6 shows the waveforms for Master mode.

When the CKE bit is set, the SDO data is valid before there is a clock edge on SCK. The change of the input sample is shown based on the state of the SMP bit. The time when the SSPBUF is loaded with the received data is shown.

FIGURE 26-6: SPI MODE WAVEFORM (MASTER MODE)



26.6.7 I²C MASTER MODE RECEPTION

Master mode reception is enabled by programming the Receive Enable bit, RCEN bit of the SSPCON2 register.

Note:	The MSSP module must be in an Idle state before the RCEN bit is set or the RCEN bit will be disregarded.

The Baud Rate Generator begins counting and on each rollover, the state of the SCL pin changes (high-to-low/low-to-high) and data is shifted into the SSPSR. After the falling edge of the eighth clock, the receive enable flag is automatically cleared, the contents of the SSPSR are loaded into the SSPBUF, the BF flag bit is set, the SSP1IF flag bit is set and the Baud Rate Generator is suspended from counting, holding SCL low. The MSSP is now in Idle state awaiting the next command. When the buffer is read by the CPU, the BF flag bit is automatically cleared. The user can then send an Acknowledge bit at the end of reception by setting the Acknowledge Sequence Enable, ACKEN bit of the SSPCON2 register.

26.6.7.1 BF Status Flag

In receive operation, the BF bit is set when an address or data byte is loaded into SSPBUF from SSPSR. It is cleared when the SSPBUF register is read.

26.6.7.2 SSPOV Status Flag

In receive operation, the SSPOV bit is set when 8 bits are received into the SSPSR and the BF flag bit is already set from a previous reception.

26.6.7.3 WCOL Status Flag

If the user writes the SSPBUF when a receive is already in progress (i.e., SSPSR is still shifting in a data byte), the WCOL bit is set and the contents of the buffer are unchanged (the write does not occur).

26.6.7.4 Typical Receive Sequence:

1. The user generates a Start condition by setting the SEN bit of the SSPCON2 register.
2. SSP1IF is set by hardware on completion of the Start.
3. SSP1IF is cleared by software.
4. User writes SSPBUF with the slave address to transmit and the R/$\overline{W}$ bit set.
5. Address is shifted out the SDA pin until all 8 bits are transmitted. Transmission begins as soon as SSPBUF is written to.
6. The MSSP module shifts in the $\overline{ACK}$ bit from the slave device and writes its value into the ACKSTAT bit of the SSPCON2 register.
7. The MSSP module generates an interrupt at the end of the ninth clock cycle by setting the SSP1IF bit.
8. User sets the RCEN bit of the SSPCON2 register and the master clocks in a byte from the slave.
9. After the 8th falling edge of SCL, SSP1IF and BF are set.
10. User clears the SSP1IF bit and reads the received byte from SSPUF, which clears the BF flag.
11. The user either clears the SSPCON2 register's ACKDT bit to receive another byte or sets the ADKDT bit to suppress further data and then initiates the acknowledge sequence by setting the ACKEN bit.
12. Master's ACK or $\overline{ACK}$ is clocked out to the slave and SSP1IF is set.
13. User clears SSP1IF.
14. Steps 8-13 are repeated for each received byte from the slave.
15. If the ACKST bit was set in step 11 then the user can send a STOP to release the bus.

26.6.8 ACKNOWLEDGE SEQUENCE TIMING

An Acknowledge sequence is enabled by setting the Acknowledge Sequence Enable bit, ACKEN bit of the SSPCON2 register. When this bit is set, the SCL pin is pulled low and the contents of the Acknowledge data bit are presented on the SDA pin. If the user wishes to generate an Acknowledge, then the ACKDT bit should be cleared. If not, the user should set the ACKDT bit before starting an Acknowledge sequence. The Baud Rate Generator then counts for one rollover period (TBRG) and the SCL pin is deasserted (pulled high). When the SCL pin is sampled high (clock arbitration), the Baud Rate Generator counts for TBRG. The SCL pin is then pulled low. Following this, the ACKEN bit is automatically cleared, the Baud Rate Generator is turned off and the MSSP module then goes into Idle mode (Figure 26-29).

26.6.8.1 WCOL Status Flag

If the user writes the SSPBUF when an Acknowledge sequence is in progress, then WCOL is set and the contents of the buffer are unchanged (the write does not occur).

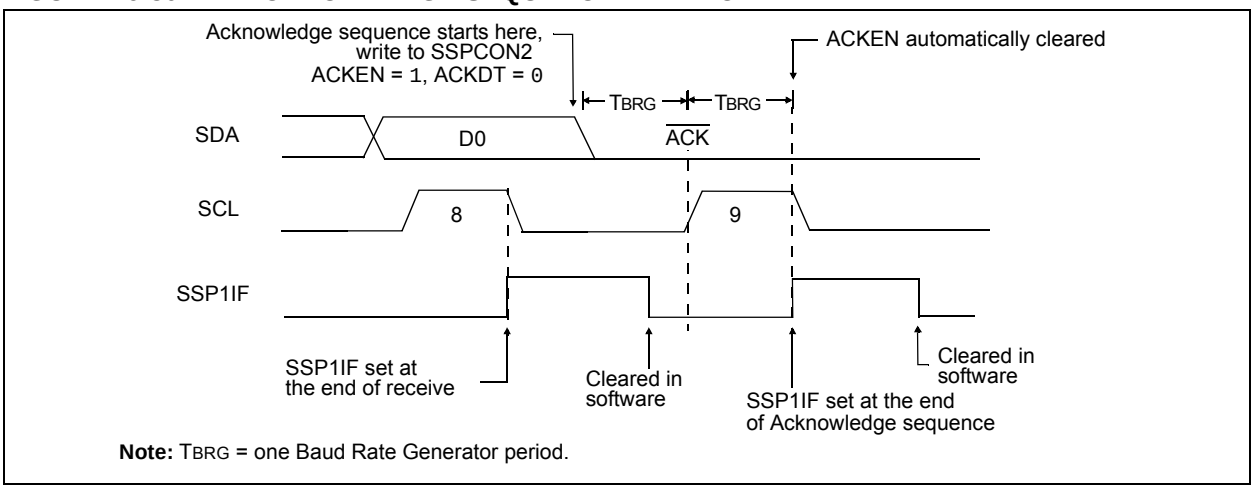
26.6.9 STOP CONDITION TIMING

A Stop bit is asserted on the SDA pin at the end of a receive/transmit by setting the Stop Sequence Enable bit, PEN bit of the SSPCON2 register. At the end of a receive/transmit, the SCL line is held low after the falling edge of the ninth clock. When the PEN bit is set, the master will assert the SDA line low. When the SDA line is sampled low, the Baud Rate Generator is reloaded and counts down to '0'. When the Baud Rate Generator times out, the SCL pin will be brought high and one TBRG (Baud Rate Generator rollover count) later, the SDA pin will be deasserted. When the SDA pin is sampled high while SCL is high, the P bit of the SSPSTAT register is set. A TBRG later, the PEN bit is cleared and the SSP1IF bit is set (Figure 26-30).

26.6.9.1 WCOL Status Flag

If the user writes the SSPBUF when a Stop sequence is in progress, then the WCOL bit is set and the contents of the buffer are unchanged (the write does not occur).

FIGURE 26-30: ACKNOWLEDGE SEQUENCE WAVEFORM



Note: TBRG = one Baud Rate Generator period.

FIGURE 26-34: BUS COLLISION DURING START CONDITION (SCL = 0)

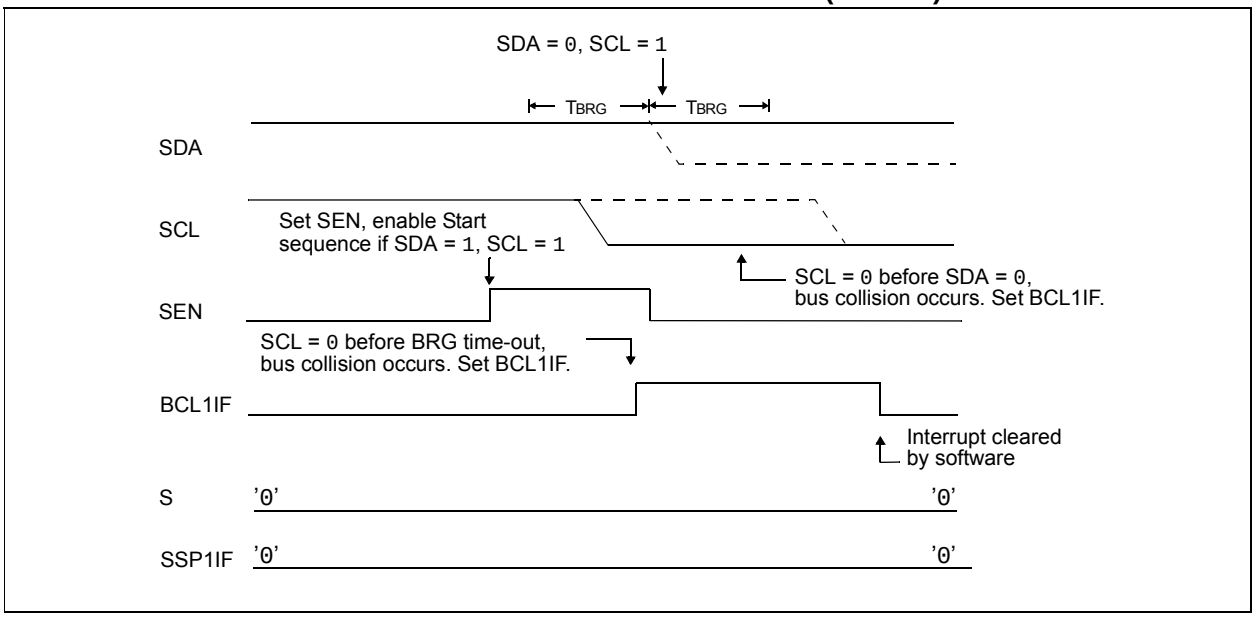


FIGURE 26-35: BRG RESET DUE TO SDA ARBITRATION DURING START CONDITION

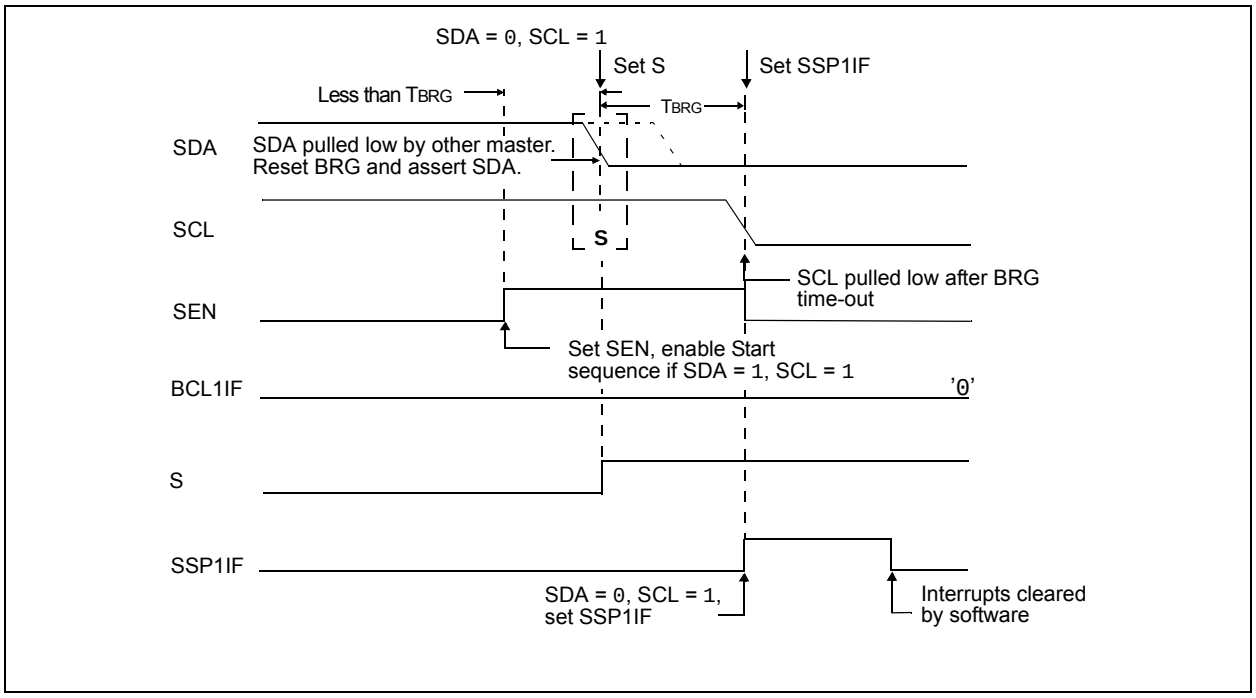
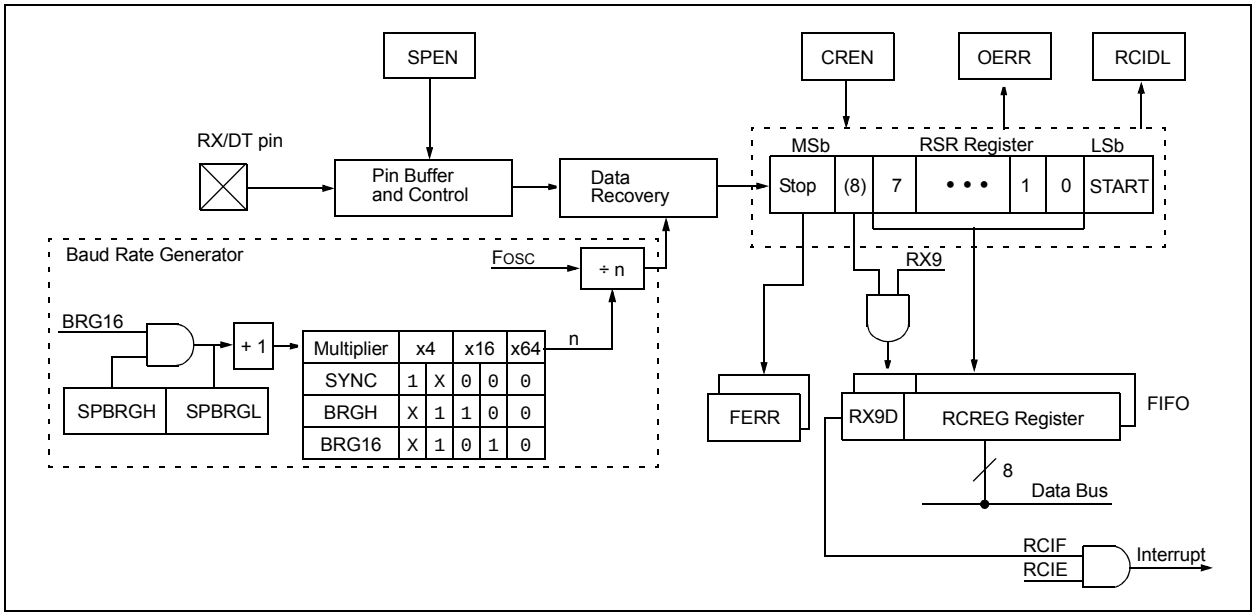


FIGURE 27-2: EUSART RECEIVE BLOCK DIAGRAM



The operation of the EUSART module is controlled through three registers:

- Transmit Status and Control (TXSTA)
- Receive Status and Control (RCSTA)
- Baud Rate Control (BAUDCON)

These registers are detailed in Register 27-1, Register 27-2 and Register 27-3, respectively.

When the receiver or transmitter section is not enabled then the corresponding RX or TX pin may be used for general purpose input and output.

TABLE 27-5: BAUD RATES FOR ASYNCHRONOUS MODES

BAUD RATE	SYNC = 0, BRGH = 0, BRG16 = 0											
	Fosc = 32.000 MHz			Fosc = 20.000 MHz			Fosc = 18.432 MHz			Fosc = 11.0592 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	—	—	—	—	—	—	—	—	—	—	—	—
1200	—	—	—	1221	1.73	255	1200	0.00	239	1200	0.00	143
2400	2404	0.16	207	2404	0.16	129	2400	0.00	119	2400	0.00	71
9600	9615	0.16	51	9470	-1.36	32	9600	0.00	29	9600	0.00	17
10417	10417	0.00	47	10417	0.00	29	10286	-1.26	27	10165	-2.42	16
19.2k	19.23k	0.16	25	19.53k	1.73	15	19.20k	0.00	14	19.20k	0.00	8
57.6k	55.55k	-3.55	3	—	—	—	57.60k	0.00	7	57.60k	0.00	2
115.2k	—	—	—	—	—	—	—	—	—	—	—	—

BAUD RATE	SYNC = 0, BRGH = 0, BRG16 = 0											
	Fosc = 8.000 MHz			Fosc = 4.000 MHz			Fosc = 3.6864 MHz			Fosc = 1.000 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	—	—	—	300	0.16	207	300	0.00	191	300	0.16	51
1200	1202	0.16	103	1202	0.16	51	1200	0.00	47	1202	0.16	12
2400	2404	0.16	51	2404	0.16	25	2400	0.00	23	—	—	—
9600	9615	0.16	12	—	—	—	9600	0.00	5	—	—	—
10417	10417	0.00	11	10417	0.00	5	—	—	—	—	—	—
19.2k	—	—	—	—	—	—	19.20k	0.00	2	—	—	—
57.6k	—	—	—	—	—	—	57.60k	0.00	0	—	—	—
115.2k	—	—	—	—	—	—	—	—	—	—	—	—

BAUD RATE	SYNC = 0, BRGH = 1, BRG16 = 0											
	Fosc = 32.000 MHz			Fosc = 20.000 MHz			Fosc = 18.432 MHz			Fosc = 11.0592 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	—	—	—	—	—	—	—	—	—	—	—	—
1200	—	—	—	—	—	—	—	—	—	—	—	—
2400	—	—	—	—	—	—	—	—	—	—	—	—
9600	9615	0.16	207	9615	0.16	129	9600	0.00	119	9600	0.00	71
10417	10417	0.00	191	10417	0.00	119	10378	-0.37	110	10473	0.53	65
19.2k	19.23k	0.16	103	19.23k	0.16	64	19.20k	0.00	59	19.20k	0.00	35
57.6k	57.14k	-0.79	34	56.82k	-1.36	21	57.60k	0.00	19	57.60k	0.00	11
115.2k	117.64k	2.12	16	113.64k	-1.36	10	115.2k	0.00	9	115.2k	0.00	5

29.0 INSTRUCTION SET SUMMARY

Each instruction is a 14-bit word containing the operation code (opcode) and all required operands. The opcodes are broken into three broad categories.

- Byte Oriented
- Bit Oriented
- Literal and Control

The literal and control category contains the most varied instruction word format.

Table 29-3 lists the instructions recognized by the MPASM™ assembler.

All instructions are executed within a single instruction cycle, with the following exceptions, which may take two or three cycles:

- Subroutine takes two cycles (CALL, CALLW)
- Returns from interrupts or subroutines take two cycles (RETURN, RETLW, RETFIE)
- Program branching takes two cycles (GOTO, BRA, BRW, BTFSS, BTFSC, DECFSZ, INCSFZ)
- One additional instruction cycle will be used when any instruction references an indirect file register and the file select register is pointing to program memory.

One instruction cycle consists of 4 oscillator cycles; for an oscillator frequency of 4 MHz, this gives a nominal instruction execution rate of 1 MHz.

All instruction examples use the format '0xhh' to represent a hexadecimal number, where 'h' signifies a hexadecimal digit.

TABLE 29-1: OPCODE FIELD DESCRIPTIONS

Field	Description
f	Register file address (0x00 to 0x7F)
W	Working register (accumulator)
b	Bit address within an 8-bit file register
k	Literal field, constant data or label
x	Don't care location (= 0 or 1). The assembler will generate code with x = 0. It is the recommended form of use for compatibility with all Microchip software tools.
d	Destination select; d = 0: store result in W, d = 1: store result in file register f. Default is d = 1.
n	FSR or INDF number. (0-1)
mm	Pre-post increment-decrement mode selection

TABLE 29-2: ABBREVIATION DESCRIPTIONS

Field	Description
PC	Program Counter
$\overline{TO}$	Time-Out bit
C	Carry bit
DC	Digit Carry bit
Z	Zero bit
PD	Power-Down bit

29.1 Read-Modify-Write Operations

Any instruction that specifies a file register as part of the instruction performs a Read-Modify-Write (R-M-W) operation. The register is read, the data is modified, and the result is stored according to either the instruction, or the destination designator 'd'. A read operation is performed on a register even if the instruction writes to that register.

TABLE 30-5: MEMORY PROGRAMMING REQUIREMENTS

Standard Operating Conditions (unless otherwise stated)							
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
		Program Memory Programming Specifications					
D110	VIHH	Voltage on $\overline{MCLR}$/VPP/RE3 pin	8.0	—	9.0	V	**(Note 3)**
D111	IDDP	Supply Current during Programming	—	—	10	mA	
D112		VDD for Bulk Erase	2.7	—	VDDMAX	V	
D113	VPEW	VDD for Write or Row Erase	VDDMIN	—	VDDMAX	V	
D114	IPPPGM	Current on $\overline{MCLR}$/VPP during Erase/Write	—	—	1.0	mA	
D115	IDDPGM	Current on VDD during Erase/Write	—		5.0	mA	
		Data EEPROM Memory					
D116	ED	Byte Endurance	100K	—	—	E/W	-40°C to +85°C
D117	VDRW	VDD for Read/Write	VDDMIN	—	VDDMAX	V	
D118	TDEW	Erase/Write Cycle Time	—	4.0	5.0	ms	
D119	TRETD	Characteristic Retention	—	40	—	Year	Provided no other specifications are violated
D120	TREF	Number of Total Erase/Write Cycles before Refresh**(2)**	100k	—	—	E/W	-40°C to +85°C
		Program Flash Memory					
D121	EP	Cell Endurance	10K	—	—	E/W	-40°C to +85°C (**Note 1**)
D122	VPR	VDD for Read	VDDMIN	—	VDDMAX	V	
D123	TIW	Self-timed Write Cycle Time	—	2	2.5	ms	
D124	TRETD	Characteristic Retention	—	40	—	Year	Provided no other specifications are violated

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Self-write and Block Erase.

2: Refer to **Section 12.2 "Using the Data EEPROM"** for a more detailed discussion on data EEPROM endurance.

3: Required only if single-supply programming is disabled.

FIGURE 30-5: CLOCK TIMING

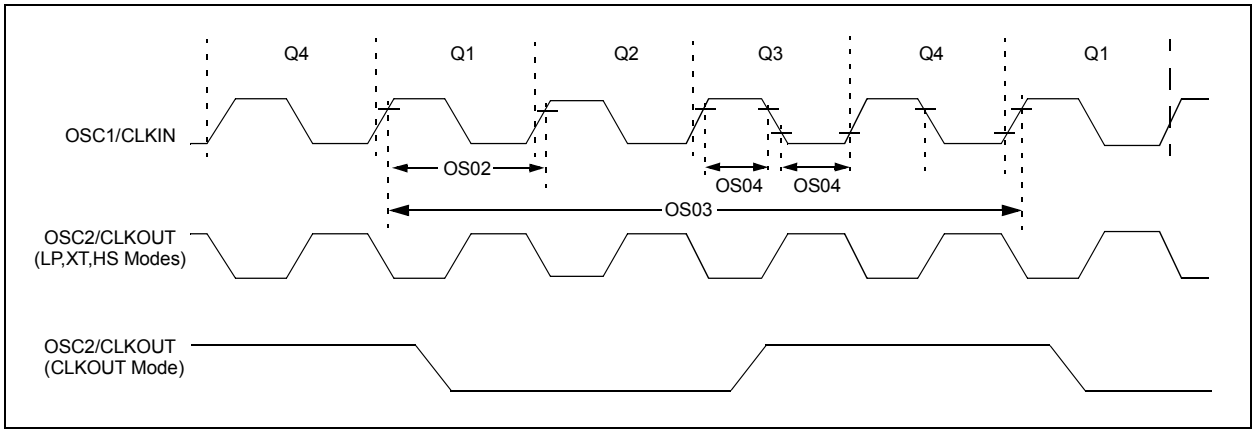


TABLE 30-6: CLOCK OSCILLATOR TIMING REQUIREMENTS

Standard Operating Conditions (unless otherwise stated)							
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
OS01	FOSC	External CLKIN Frequency(1)	DC	—	0.5	MHz	EC Oscillator mode (low)
			DC	—	4	MHz	EC Oscillator mode (medium)
			DC	—	20	MHz	EC Oscillator mode (high)
		Oscillator Frequency(1)	—	32.768	—	kHz	LP Oscillator mode
			0.1	—	4	MHz	XT Oscillator mode
			1	—	4	MHz	HS Oscillator mode
			1	—	20	MHz	HS Oscillator mode, VDD > 2.7V
			DC	—	4	MHz	RC Oscillator mode, VDD > 2.0V
OS02	TOSC	External CLKIN Period(1)	27	—	∞	μs	LP Oscillator mode
			250	—	∞	ns	XT Oscillator mode
			50	—	∞	ns	HS Oscillator mode
			50	—	∞	ns	EC Oscillator mode
		Oscillator Period(1)	—	30.5	—	μs	LP Oscillator mode
			250	—	10,000	ns	XT Oscillator mode
			50	—	1,000	ns	HS Oscillator mode
			250	—	—	ns	RC Oscillator mode
OS03	TCY	Instruction Cycle Time(1)	200	TCY	DC	ns	TCY = 4/FOSC
OS04*	TosH, TosL	External CLKIN High, External CLKIN Low	2	—	—	μs	LP oscillator
			100	—	—	ns	XT oscillator
			20	—	—	ns	HS oscillator
OS05*	TosR, TosF	External CLKIN Rise, External CLKIN Fall	0	—	∞	ns	LP oscillator
			0	—	∞	ns	XT oscillator
			0	—	∞	ns	HS oscillator

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min" values with an external clock applied to OSC1 pin. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

FIGURE 30-10: TIMER0 AND TIMER1 EXTERNAL CLOCK TIMINGS

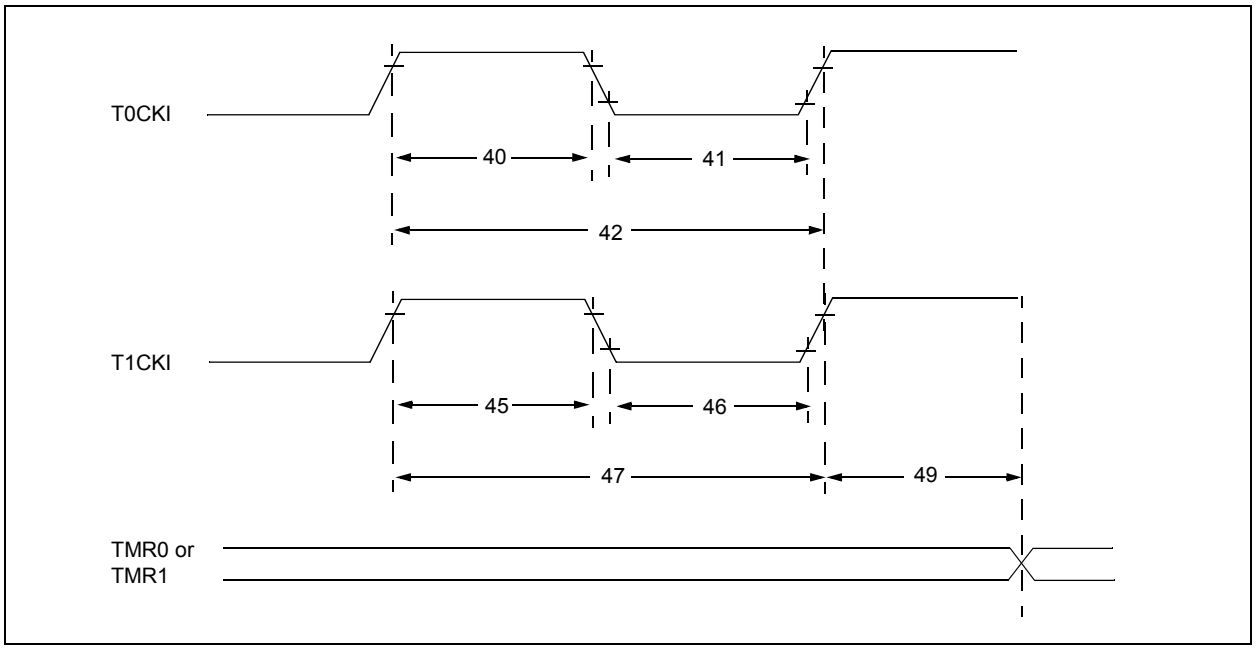


TABLE 30-11: TIMER0 AND TIMER1 EXTERNAL CLOCK REQUIREMENTS

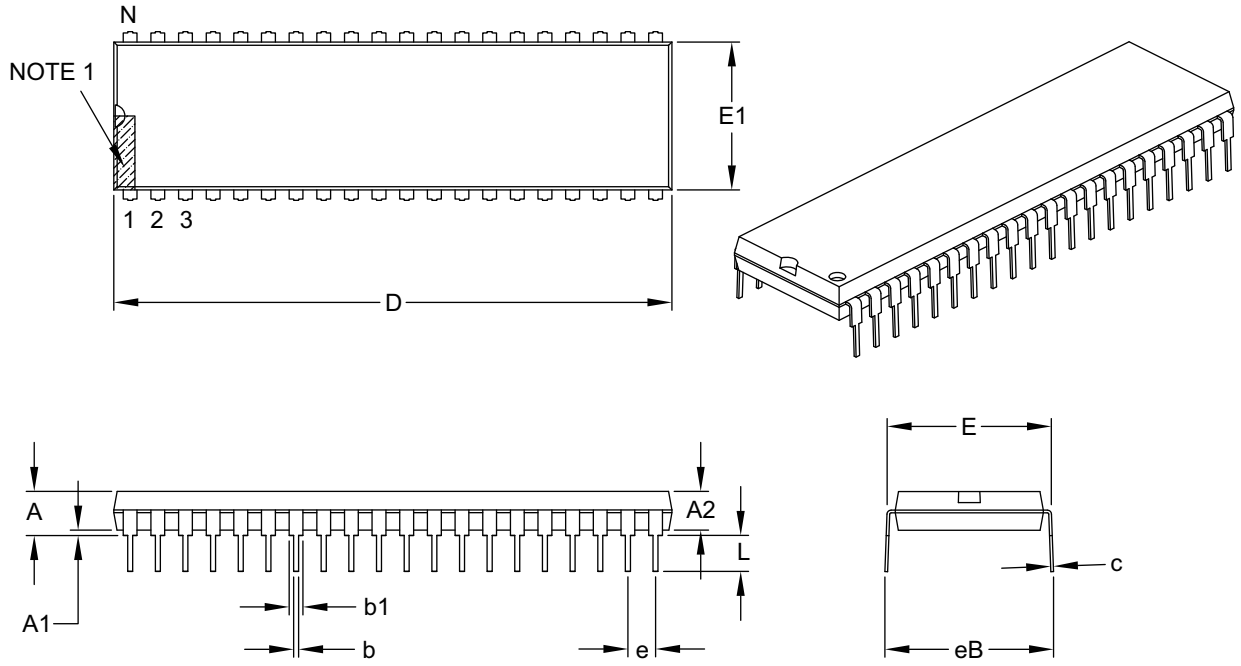
Standard Operating Conditions (unless otherwise stated)								
Param No.	**Sym.**	**Characteristic**		**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
40*	TT0H	T0CKI High Pulse Width	No Prescaler	0.5 TCY + 20	—	—	ns	
			With Prescaler	10	—	—	ns	
41*	TT0L	T0CKI Low Pulse Width	No Prescaler	0.5 TCY + 20	—	—	ns	
			With Prescaler	10	—	—	ns	
42*	TT0P	T0CKI Period		Greater of: 20 or TCY + 40 / N	—	—	ns	N = prescale value (2, 4, ..., 256)
45*	TT1H	T1CKI High Time	Synchronous, No Prescaler	0.5 TCY + 20	—	—	ns	
			Synchronous, with Prescaler	15	—	—	ns	
			Asynchronous	30	—	—	ns	
46*	TT1L	T1CKI Low Time	Synchronous, No Prescaler	0.5 TCY + 20	—	—	ns	
			Synchronous, with Prescaler	15	—	—	ns	
			Asynchronous	30	—	—	ns	
47*	TT1P	T1CKI Input Period	Synchronous	Greater of: 30 or TCY + 40 / N	—	—	ns	N = prescale value (1, 2, 4, 8)
			Asynchronous	60	—	—	ns	
48	FT1	Timer1 Oscillator Input Frequency Range (oscillator enabled by setting bit T1OSCEN)		32.4	32.768	33.1	kHz	
49*	TCKEZTMR1	Delay from External Clock Edge to Timer Increment		2 TOSC	—	7 TOSC	—	Timers in Sync mode

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

40-Lead Plastic Dual In-Line (P) – 600 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		40	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.250
Molded Package Thickness	A2	.125	–	.195
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.590	–	.625
Molded Package Width	E1	.485	–	.580
Overall Length	D	1.980	–	2.095
Tip to Seating Plane	L	.115	–	.200
Lead Thickness	c	.008	–	.015
Upper Lead Width	b1	.030	–	.070
Lower Lead Width	b	.014	–	.023
Overall Row Spacing §	eB	–	–	.700

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-016B

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	[X](1)	-	X	/XX	XXX
Device	Tape and Reel Option		Temperature Range	Package	Pattern

Device:	PIC16F1784, PIC16LF1784, PIC16F1786, PIC16LF1786, PIC16F1787, PIC16LF1787	
Tape and Reel Option:	Blank T	= Standard packaging (tube or tray) = Tape and Reel(1)
Temperature Range:	I E	= -40°C to +85°C (Industrial) = -40°C to +125°C (Extended)
Package:(2)	ML MV P PT SP SO SS	= QFN = UQFN = PDIP = TQFP = SPDIP = SOIC = SSOP
Pattern:	QTP, SQTP, Code or Special Requirements (blank otherwise)	

Examples:

a) PIC16LF1784/7- I/P
Industrial temperature
PDIP package

b) PIC16F1786- E/SS
Extended temperature,
SSOP package

Note 1: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.

2: Small form-factor packaging options may be available. Please check www.microchip.com/packaging for small-form factor package availability, or contact your local Sales Office.